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Product Preview **Dual NPN Bias Resistor Transistors R1 = 2.2 k\Omega, R2 = 47 k\Omega**

NPN Transistors with Monolithic Bias Resistor Network

This series of digital transistors is designed to replace a single device and its external resistor bias network. The Bias Resistor Transistor (BRT) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. The BRT eliminates these individual components by integrating them into a single device. The use of a BRT can reduce both system cost and board space.

Features

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

 $(T_A = 25^{\circ}C, \text{ common for } Q_1 \text{ and } Q_2, \text{ unless otherwise noted})$

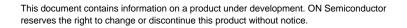
Rating	Symbol	Max	Unit
Collector-Base Voltage	V _{CBO}	50	Vdc
Collector-Emitter Voltage	V _{CEO}	50	Vdc
Collector Current – Continuous	Ι _C	100	mAdc
Input Forward Voltage	V _{IN(fwd)}	12	Vdc
Input Reverse Voltage	V _{IN(rev)}	5	Vdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ORDERING INFORMATION

Device	Package	Shipping [†]
NSVMUN5235DW1T1G	SOT-363 (Pb-Free)	3,000 / Tape & Reel

⁺For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

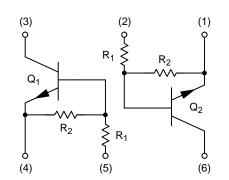




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PIN CONNECTIONS



MARKING DIAGRAM



7M = Specific Device Code M = Date Code* • = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

Semiconductor Components Industries, LLC, 2016
September, 2016 – Rev. P0

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
ONE JUNCTION HEATED			
Total Device Dissipation $T_A = 25^{\circ}C$ (Note 1) (Note 2) Derate above $25^{\circ}C$ (Note 1) (Note 2)	PD	187 256 1.5 2.0	mW mW/°C
Thermal Resistance,(Note 1)Junction to Ambient(Note 2)	R _{θJA}	670 490	°C/W

BOTH JUNCTION HEATED (Note 3)

Total Device Dissipation $T_A = 25^{\circ}C$ (Note 1) (Note 2) Derate above 25^{\circ}C (Note 1) (Note 2)	PD	250 385 2.0 3.0	m₩ mW/°C
Thermal Resistance, Junction to Ambient (Note 1) (Note 2)	R _{θJA}	493 325	°C/W
Thermal Resistance, Junction to Lead (Note 1) (Note 2)	R _{θJL}	188 208	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

FR-4 @ Minimum Pad.
FR-4 @ 1.0 × 1.0 Inch Pad.
Both junction heated values assume total power is sum of two equally powered channels.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$, common for Q_1 and Q_2 , unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
DFF CHARACTERISTICS					•
Collector-Base Cutoff Current $(V_{CB} = 50 \text{ V}, I_E = 0)$	I _{СВО}	_	_	100	nAdc
Collector-Emitter Cutoff Current ($V_{CE} = 50 \text{ V}, I_B = 0$)	I _{CEO}	-	_	500	nAdc
Emitter-Base Cutoff Current ($V_{EB} = 6.0 \text{ V}, I_C = 0$)	I _{EBO}	-	_	0.2	mAdc
Collector-Base Breakdown Voltage $(I_C = 10 \ \mu\text{A}, I_E = 0)$	V _{(BR)CBO}	50	_	-	Vdc
Collector-Emitter Breakdown Voltage (Note 4) $(I_C = 2.0 \text{ mA}, I_B = 0)$	V _{(BR)CEO}	50	_	_	Vdc
DN CHARACTERISTICS					
DC Current Gain (Note 4) (I _C = 5.0 mA, V _{CE} = 10 V)	h _{FE}	80	140	-	
Collector-Emitter Saturation Voltage (Note 4) ($I_C = 10 \text{ mA}, I_B = 1.0 \text{ mA}$)	V _{CE(sat)}	_	_	0.25	V
Input Voltage (Off) $(V_{CE} = 5.0 \text{ V}, I_C = 100 \mu\text{A})$	V _{i(off)}	-	0.6	-	Vdc
Input Voltage (On) (V _{CE} = 0.2 V, I _C = 5.0 mA)	V _{i(on)}	_	0.8	_	Vdc
Output Voltage (On) ($V_{CC} = 5.0 \text{ V}, V_B = 2.5 \text{ V}, R_L = 1.0 \text{ k}\Omega$)	V _{OL}	-	_	0.2	Vdc
Output Voltage (Off) (V _{CC} = 5.0 V, V _B = 0.5 V, R _L = 1.0 k Ω)	V _{OH}	4.9	_	_	Vdc
Input Resistor	R1	1.5	2.2	2.9	kΩ
Resistor Ratio	R ₁ /R ₂	0.038	0.047	0.056	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulsed Condition: Pulse Width = 300 ms, Duty Cycle $\leq 2\%$.

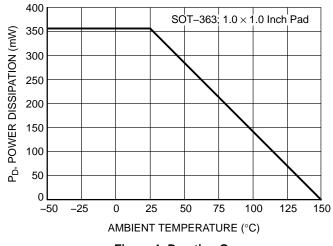
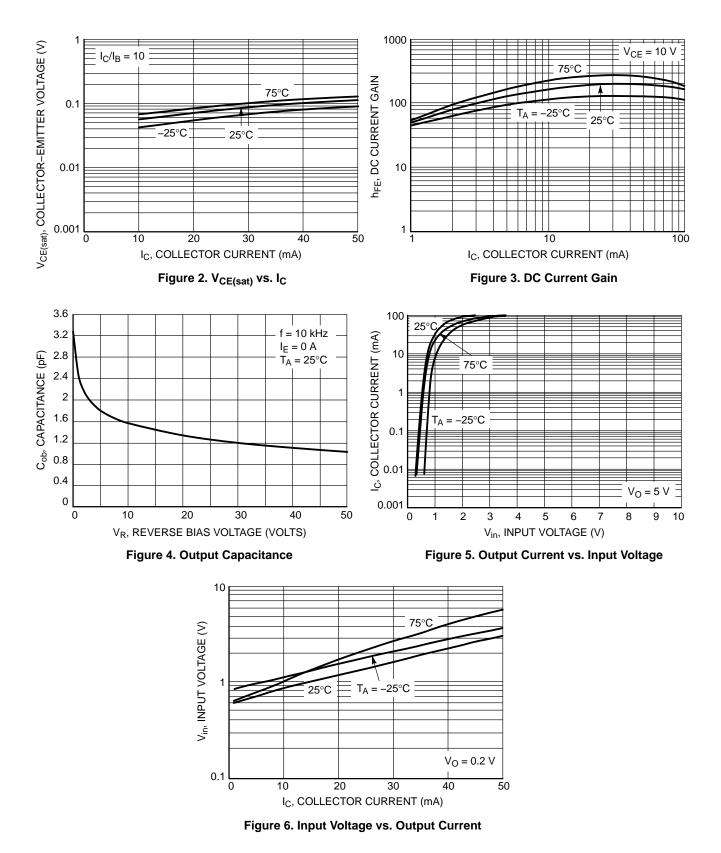
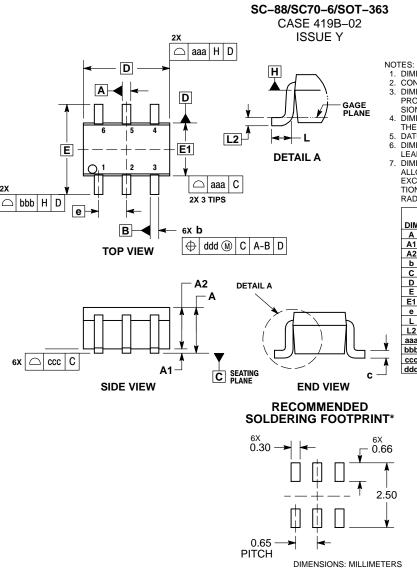


Figure 1. Derating Curve

TYPICAL CHARACTERISTICS



PACKAGE DIMENSIONS



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- DIMENSIONING AND TOLERANCING PER ASME 174.5M, 1994 CONTROLLING DIMENSION: MILLIMETERS. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRU-SIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE DUADO DODY. WHEN SHALL NOT EXCEED 0.20 PER END.
- THE PLASTIC BODY AND DATUM H. DATUMS A AND B ARE DETERMINED AT DATUM H.
- DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
- DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION & AT MAXIMUM MATERIAL CONDI-TION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α			1.10			0.043	
A1	0.00		0.10	0.000		0.004	
A2	0.70	0.90	1.00	0.027	0.035	0.039	
b	0.15	0.20	0.25	0.006	0.008	0.010	
c	0.08	0.15	0.22	0.003	0.006	0.009	
D	1.80	2.00	2.20	0.070	0.078	0.086	
Е	2.00	2.10	2.20	0.078	0.082	0.086	
E1	1.15	1.25	1.35	0.045	0.049	0.053	
е	0.65 BSC			0	026 BSC		
L	0.26	0.36	0.46	0.010	0.014	0.018	
L2	0.15 BSC			(0.006 BSC		
aaa	0.15				0.006		
bbb	0.30				0.012		
CCC	0.10				0.004		
ddd	0.10				0.004		

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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